

Previous Involvement

Aalto University	FINLAND	I-Shou University	TAIWAN
Adamant Co., Ltd.	JAPAN	Ibaraki University	JAPAN
AGC Electronics America	JAPAN	Illinois Institute of Technology	USA
AIST	JAPAN	IMEC/Holst Centre	THE NETHERLANDS
American University in Cairo	EGYPT	IMEP-LAHC	FRANCE
Analog Devices	USA	IMEP-LAHC (MINATEC)	FRANCE
Angstrom Space Technology Centre	SWEDEN	Imperial College London	UK
AOI Electronics Co., Ltd.	JAPAN	Indiana University-Purdue University Indianapolis	USA
ARPA-E, U.S. Department of Energy	USA	Inha University	SOUTH KOREA
Asahi Glass Co., Ltd.	JAPAN	Integrity Research Institute	USA
ATK GASL	USA	IOP Publishing	UK
Austrian Institute of Technology GmbH (AIT)	AUSTRIA	Iran University of Science and Technology	IRAN
Ben-Gurion University	ISRAEL	IREC-Catalonia Institute for Energy Research	SPAIN
Boston University	USA	Irvine Sensors Corporation	USA
Case Western Reserve University	USA	ISC8 Inc.	USA
Castor & Wheel Pte Ltd.	JAPAN	Isfahan University of Technology	IRAN
Catholic University of Daegu	SOUTH KOREA	Japan Science and Technology Agency	JAPAN
CEA	FRANCE	Johns Hopkins University	USA
Chalmers University of Technology	SWEDEN	Kansai University	JAPAN
China University of Geosciences	CHINA	Katholieke Universiteit Leuven	BELGIUM
Chinese University of Hong Kong	HONG KONG	Kobe University	JAPAN
Chongqing University	CHINA	Konishiyasu Co., Ltd.	JAPAN
Chosun University	SOUTH KOREA	Korea Advanced Institute of Science and Technology (KAIST)	SOUTH KOREA
Chubu University	JAPAN	Korea Institute of Machinery & Materials (KIMM)	SOUTH KOREA
City University of Hong Kong	HONG KONG	Korea Institute of Science and Technology (KIST)	SOUTH KOREA
Cleveland State University	USA	Korea Polytechnic University	SOUTH KOREA
CMC Microsystems	CANADA	KRISS	SOUTH KOREA
CMP	FRANCE	Kwangwoon University	SOUTH KOREA
Commonwealth Scientific and Industrial Research Organization	AUSTRALIA	Kyoto University	JAPAN
Cornell University	USA	Kyung Hee University	SOUTH KOREA
CUNY Energy Institute	USA	Kyushu Institute of Technology	JAPAN
Dai Nippon Printing Co., Ltd.	JAPAN	LAAS - CNRS	FRANCE
DNP Co., Ltd.	JAPAN	LAPIS Semiconductor Co., Ltd.	JAPAN
Dow Chemical	USA	Lehigh University	USA
DRDC Valcartier	CANADA	LG Electronics	SOUTH KOREA
Drexel University	USA	Louisiana Tech University	USA
Dreyer Medical Clinic	USA	Massachusetts Institute of Technology	USA
DSO National Laboratory	SINGAPORE	MEMS & Nanotechnology Exchange	USA
Duke University	USA	MESA+ Institution for Nanotechnology	THE NETHERLANDS
Echemics	USA	Michigan State University	USA
École de Technologie Supérieure	CANADA	Michigan Technological University	USA
Ecole Polytechnique Fédérale de Lausanne (EPFL)	SWITZERLAND	Middle East Technical University NCC	TURKEY
Electret Alliance	JAPAN	Murata Manufacturing Company, Ltd.	JAPAN
Electricity Generating Authority of Thailand	THAILAND	Nagoya University	JAPAN
Empower Materials	USA	Nanyang Technological University	SINGAPORE
ESIEE Paris	FRANCE	National Cheng Kung University	TAIWAN
EV Group Inc.	USA	National Chiao Tung University	TAIWAN
Ewha Womans University	SOUTH KOREA	National Institute of Advanced Industrial Science and Technology (AIST)	JAPAN
Fraunhofer Institute for Electronic Nano Systems	GERMANY	National Taiwan University	TAIWAN
Fraunhofer Institute for Integrated Circuits	GERMANY	National Tsing Hua University	TAIWAN
Fraunhofer Institute for Silicon Technology ISIT	GERMANY	National University of Singapore	SINGAPORE
Fraunhofer ISE	GERMANY	Naval Research Laboratory	USA
Frostburg State University	USA	Nihon University	JAPAN
Fujitsu Laboratories, Ltd.	JAPAN	Nippon Hoso Kyokai Corporation Information	JAPAN
Georgia Institute of Technology	USA	NMEMS Technology Research Organization	JAPAN
Gifu University	JAPAN	North Carolina State University	USA
Grenoble Electrical Engineering Laboratory	FRANCE	Northeastern University	USA
GS Nanotech	SOUTH KOREA	Novosibirsk State Technical University	RUSSIAN FEDERATION
Guangzhou Institute of Energy Conversion	CHINA	OMRON Corporation	JAPAN
Harbin Institute of Technology	CHINA	ONERA	FRANCE
Hewlett Packard Laboratories	USA	Oregon State University	USA
Hiroshima University	JAPAN	Osaka Prefecture University	JAPAN
Hokkaido University	JAPAN	Panasonic Corporation	JAPAN
Hokuriku Electric Industry Co.,Ltd.	JAPAN	Peking University	CHINA
Holst Centre/imec	THE NETHERLANDS	Pennsylvania State University	USA
Honda Research & Development	JAPAN	Pohang University of Science & Technology (POSTECH)	SOUTH KOREA
HSG-IMIT	GERMANY	Politecnico di Torino	ITALY

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DECEMBER 1 - 4

	SOUTH KOREA		
POSTECH	USA	University of Missouri	USA
Potomac Photonics, Inc.	USA	University of Nottingham	UK
Purdue University	USA	University of Sherbrooke	CANADA
Rensselaer Polytechnic Institute	USA	University of South Florida	USA
Ritsumeikan University	JAPAN	University of Southampton	UK
Robert Bosch LLC	GERMANY	University of Southern California	USA
Rohm Co., Ltd.	JAPAN	University of Texas, Austin	USA
Saginomiya Seisakusho, Inc.	JAPAN	University of Texas, Dallas	USA
Samsung Advanced Institute of Technology	SOUTH KOREA	University of Texas, San Antonio	USA
Samsung Electro-Mechanics Co., Ltd.	SOUTH KOREA	University of Tokyo	JAPAN
Seoul National University	SOUTH KOREA	University of Ulsan	SOUTH KOREA
Shanghai Institute of Technology	CHINA	University of Utah	USA
Shanghai Jiao Tong University	CHINA	University of Waterloo	CANADA
Shizuoka University	JAPAN	University Paris-Est	FRANCE
Simon Fraser University	CANADA	University Pierre et Marie Curie	FRANCE
Singapore University of Technology and Design	SINGAPORE	US Army RDECOM AMRDEC	USA
Sogang University	SOUTH KOREA	US Army Research Laboratory	USA
SPP Process Technology Systems Limited	UK	Veratag	USA
SRI International	USA	Vestfold University College	NORWAY
Stanford University	USA	Victoria University of Wellington	NEW ZEALAND
Stanley Associates	USA	Virginia Tech	USA
Stevens Institute of Technology	USA	VTT Technical Research Centre	FINLAND
Stichting IMEC Nederlands	THE NETHERLANDS	Waseda University	JAPAN
STMicroelectronics	ITALY	Washington State University	USA
SUNY Binghamton	USA	Wayne State University	USA
Takion Co., Ltd.	JAPAN	Xiamen University	CHINA
TE Connectivity	SOUTH KOREA	Yamagata University	JAPAN
Technical University of Denmark	DENMARK	Yamatake Corporation	JAPAN
Technische Universität Braunschweig	GERMANY	Yonsei University	SOUTH KOREA
Technische Universität Darmstadt	GERMANY		
Technische Universität München	GERMANY		
Technische Universitaet Eindhoven	THE NETHERLANDS		
Texas Instruments, Inc.	USA		
Tohoku University	JAPAN		
Tokyo Ohka Kogyo Co., Ltd.	JAPAN		
Tokyo University of Agriculture and Technology	JAPAN		
Tokyo University of Science	JAPAN		
Toshiba Co.	JAPAN		
Toshiba Samsung Storage Technology	JAPAN		
Triadelphia Design Group	USA		
Tsinghua University	CHINA		
Tuskegee University	USA		
Ulsan National Institute of Sience & Technology (UNIST)	SOUTH KOREA		
Universidad Autonoma de Barcelona	SPAIN		
Universite Claude Bernard Lyon 1	FRANCE		
Université de Savoie	FRANCE		
Universiti Teknologi Petronas	MALAYSIA		
University of Alabama	USA		
University of Barcelona	SPAIN		
University of Birmingham	UK		
University of Bremen	GERMANY		
University of Bristol	UK		
University of California, Berkeley	USA		
University of California, Los Angeles	USA		
University of California, San Diego	USA		
University of Cambridge	UK		
University of Cincinnati	USA		
University of Delaware	USA		
University of Florida	USA		
University of Freiburg – IMTEK	GERMANY		
University of Hong Kong	HONG KONG		
University of Hyogo	JAPAN		
University of Illinois, Urbana-Champaign	USA		
University of Louisville	USA		
University of Maryland	USA		
University of Massachusetts, Lowell	USA		
University of Michigan	USA		
University of Minnesota	USA		

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